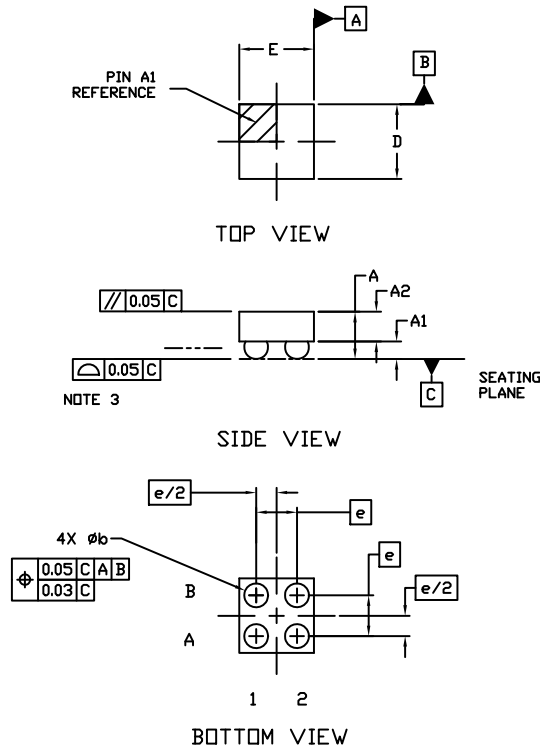


WLCSP4, 0.64x0.64x0.40
CASE 567XW
ISSUE A

DATE 13 NOV 2019



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.

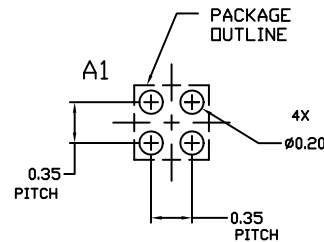
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.360	0.405	0.450
A1	0.130	0.150	0.170
A2	0.255 REF		
b	0.180	0.210	0.240
D	0.610	0.640	0.670
E	0.610	0.640	0.670
e	0.350 BSC		

GENERIC MARKING DIAGRAM*



X = Specific Device Code
M = Month

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

- * For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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DESCRIPTION:	WLCSP4, 0.64x0.64x0.40	PAGE 1 OF 1

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